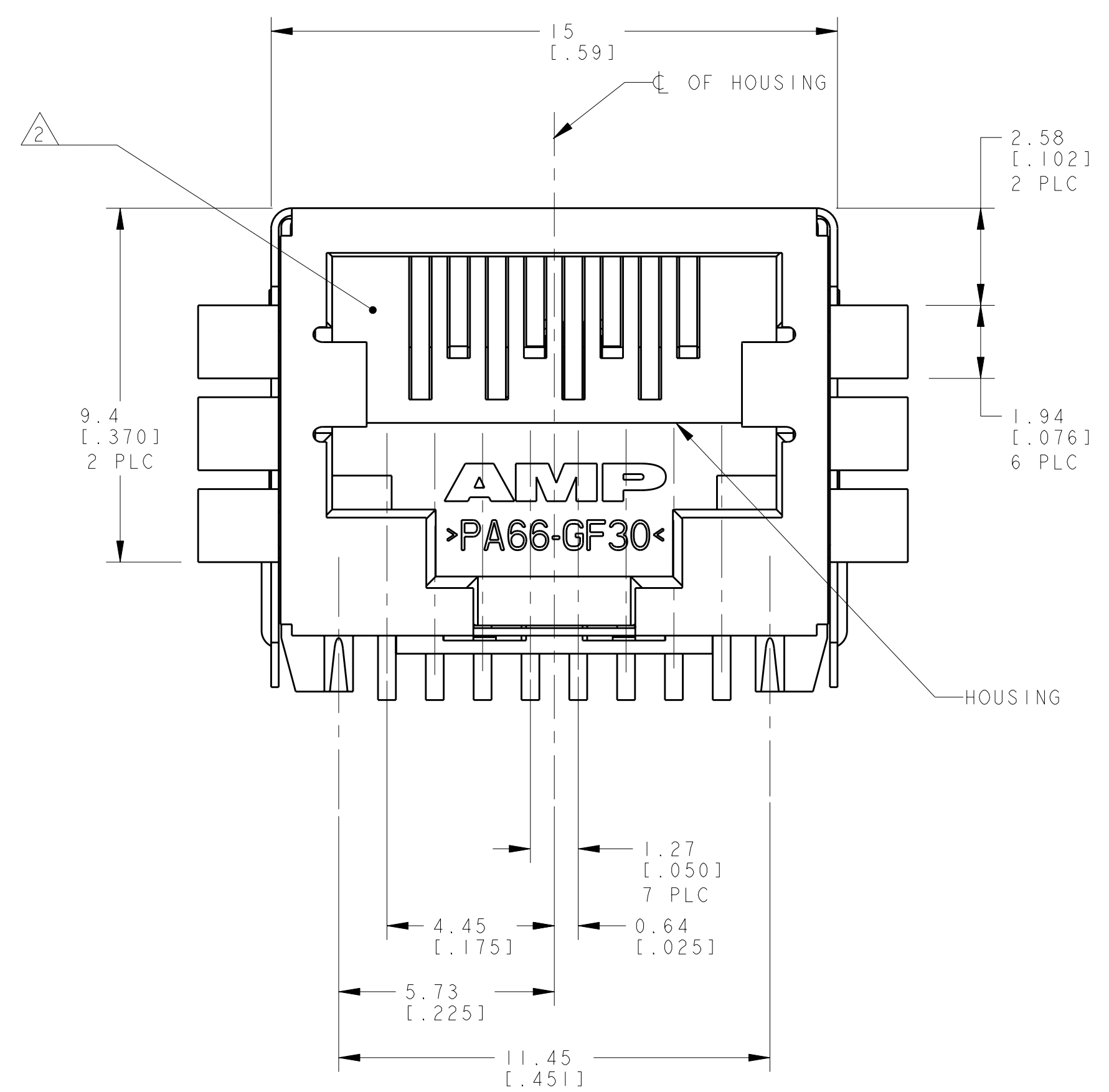
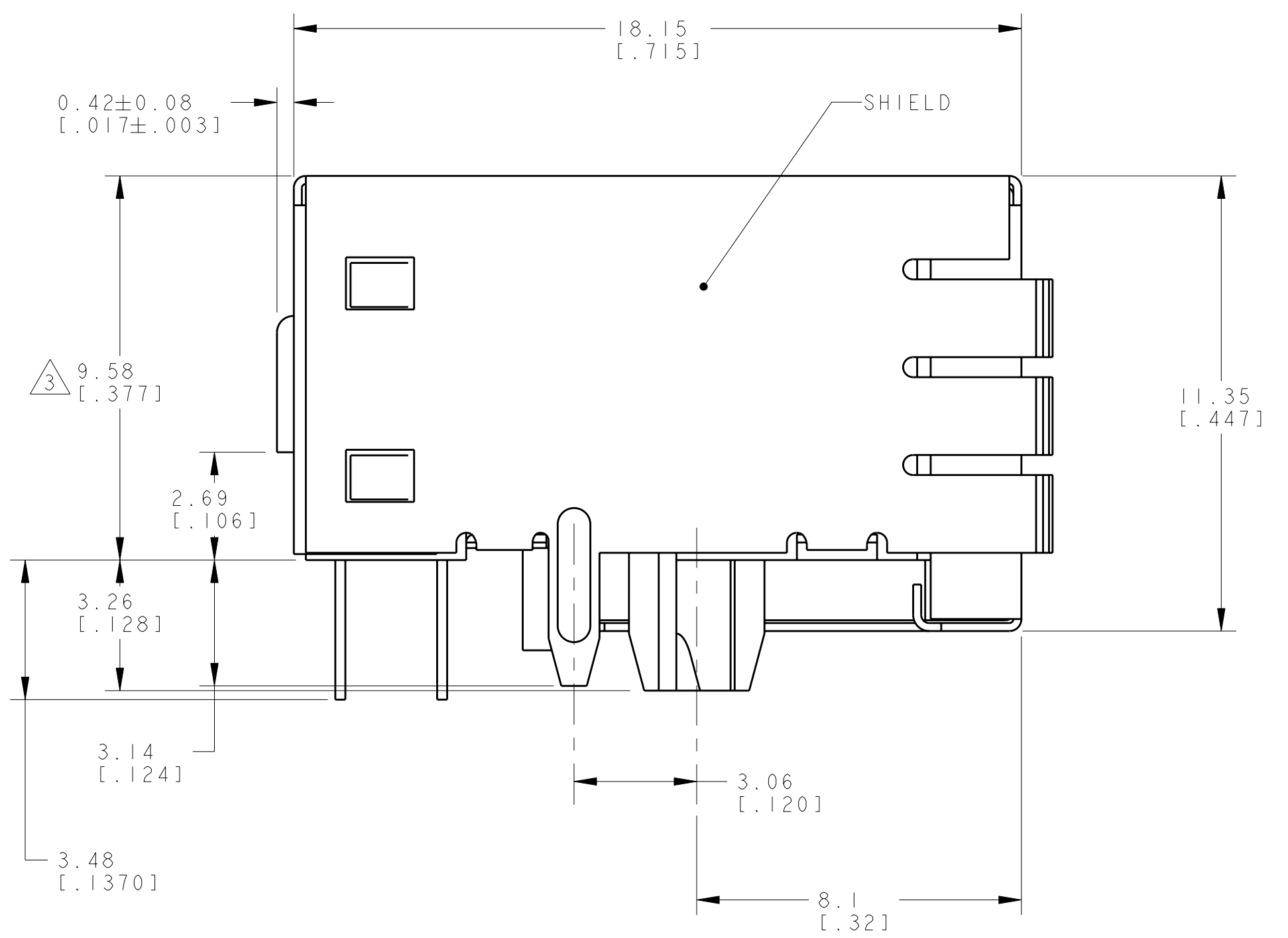
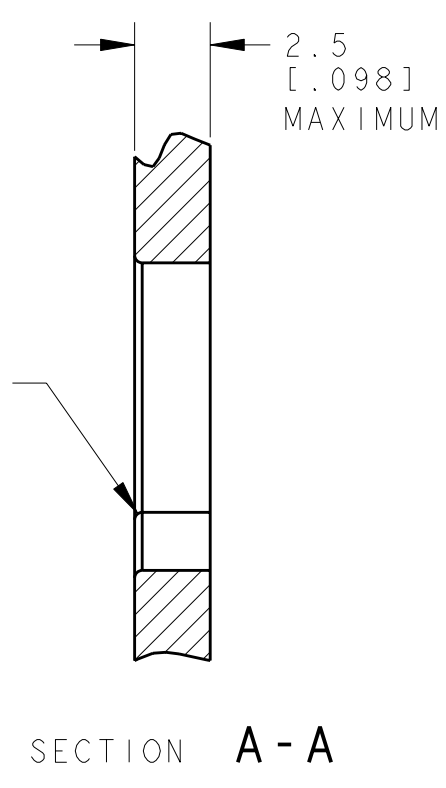
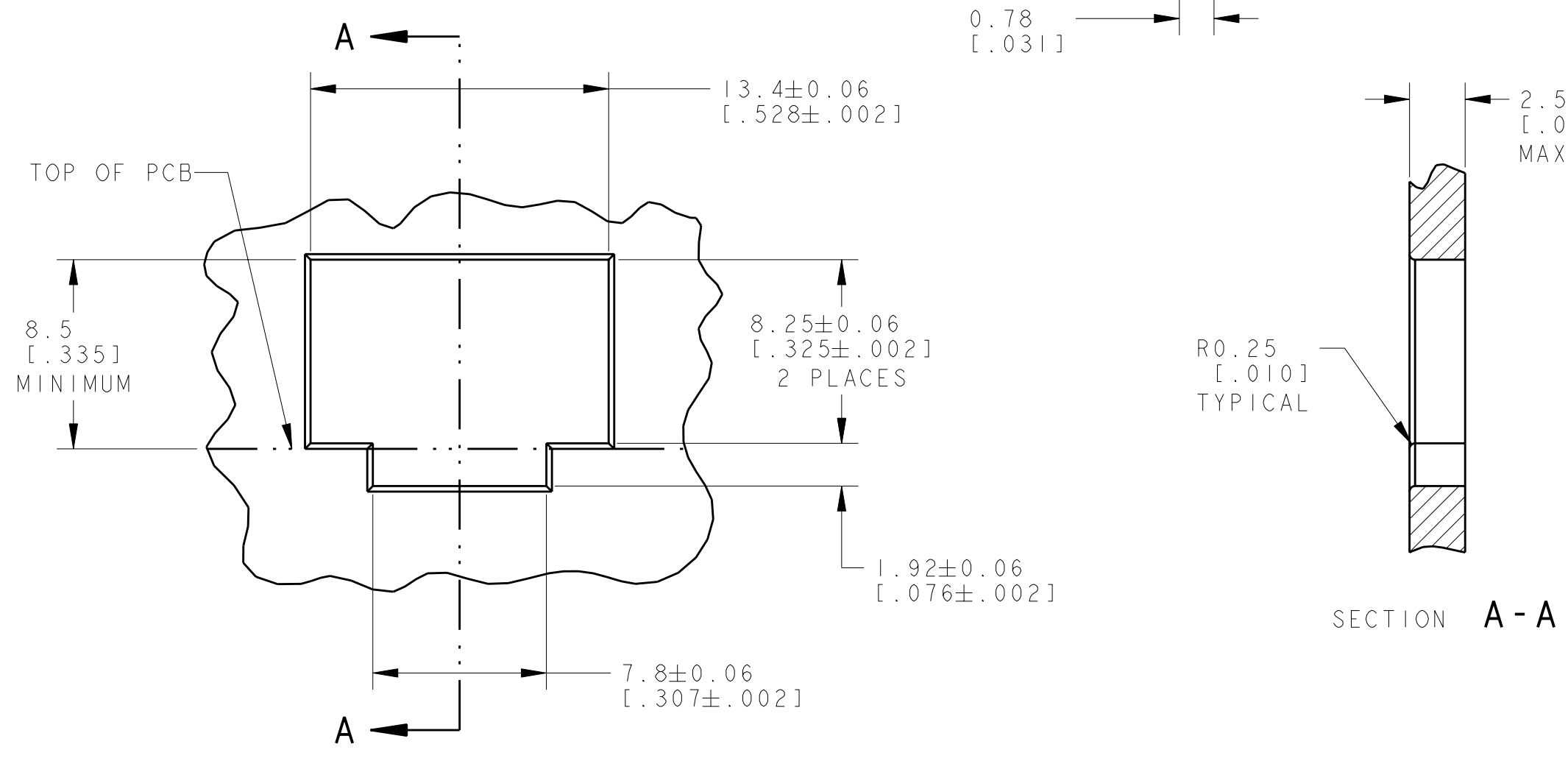
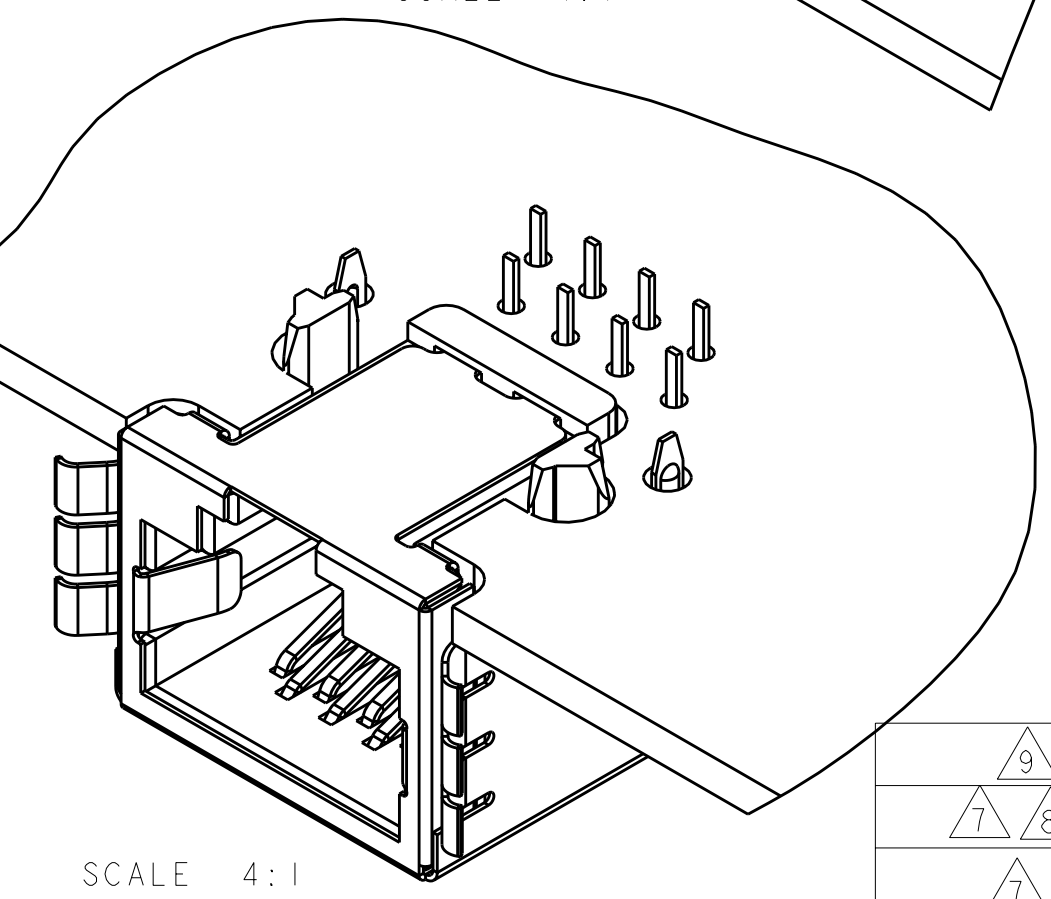
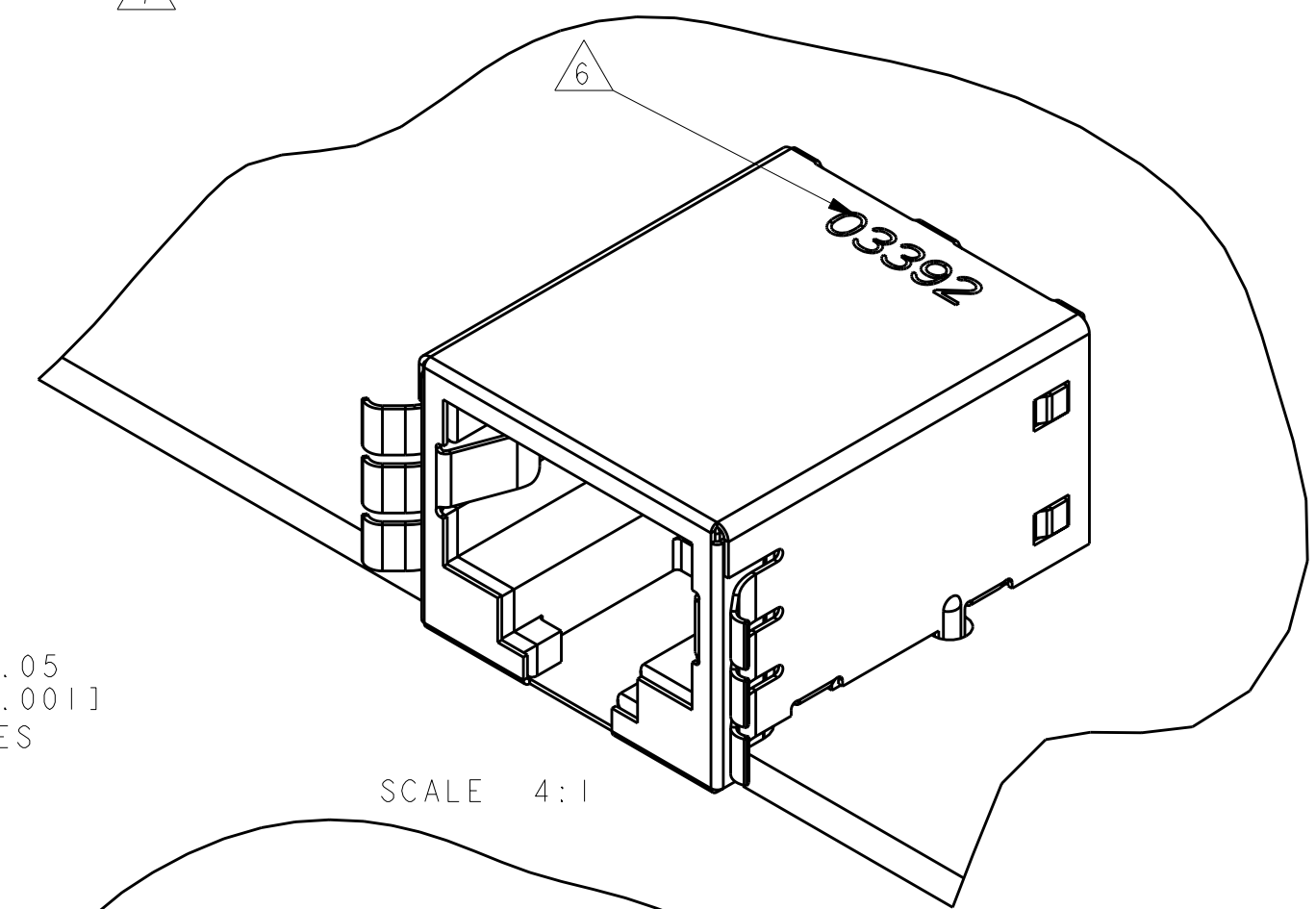
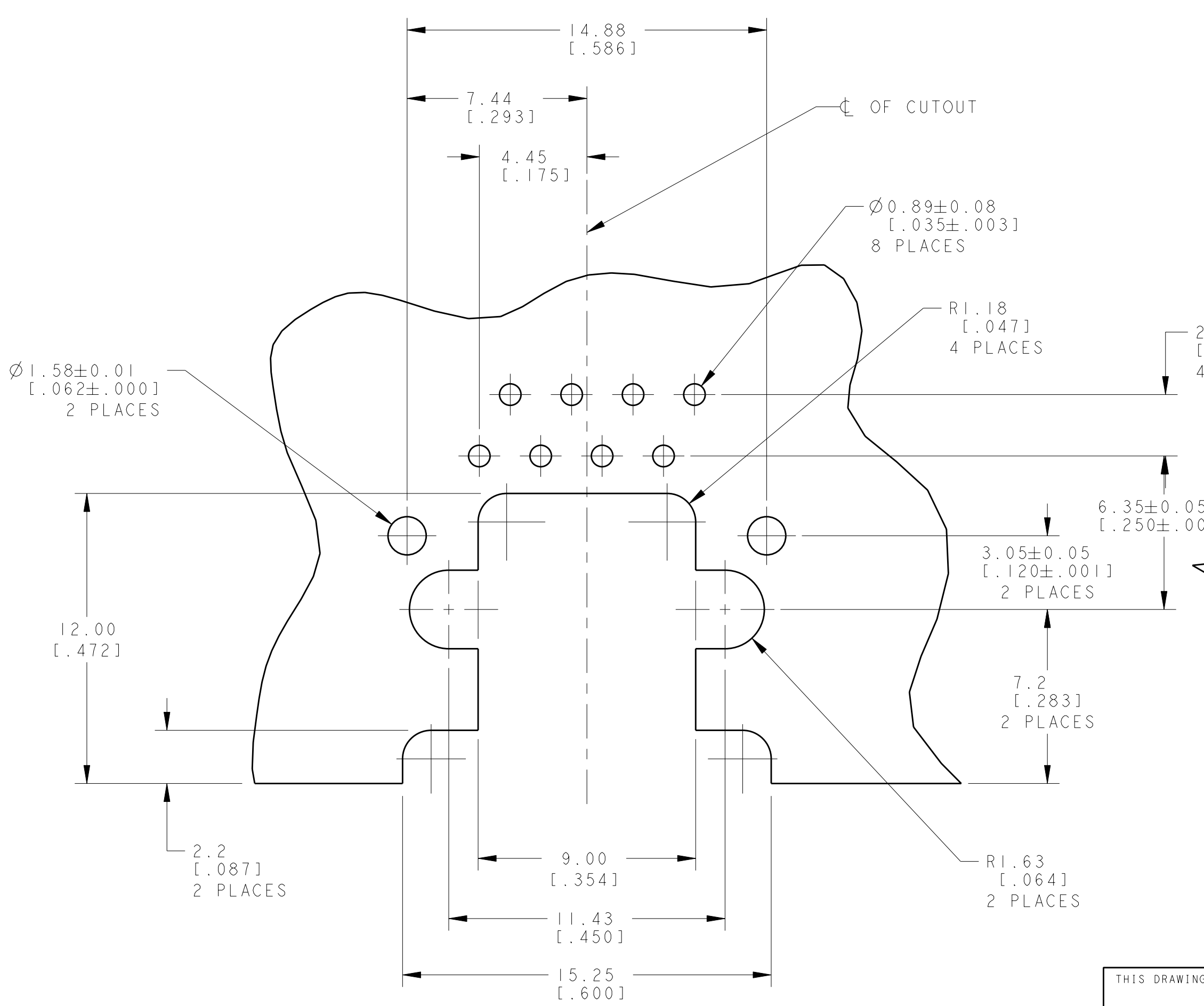
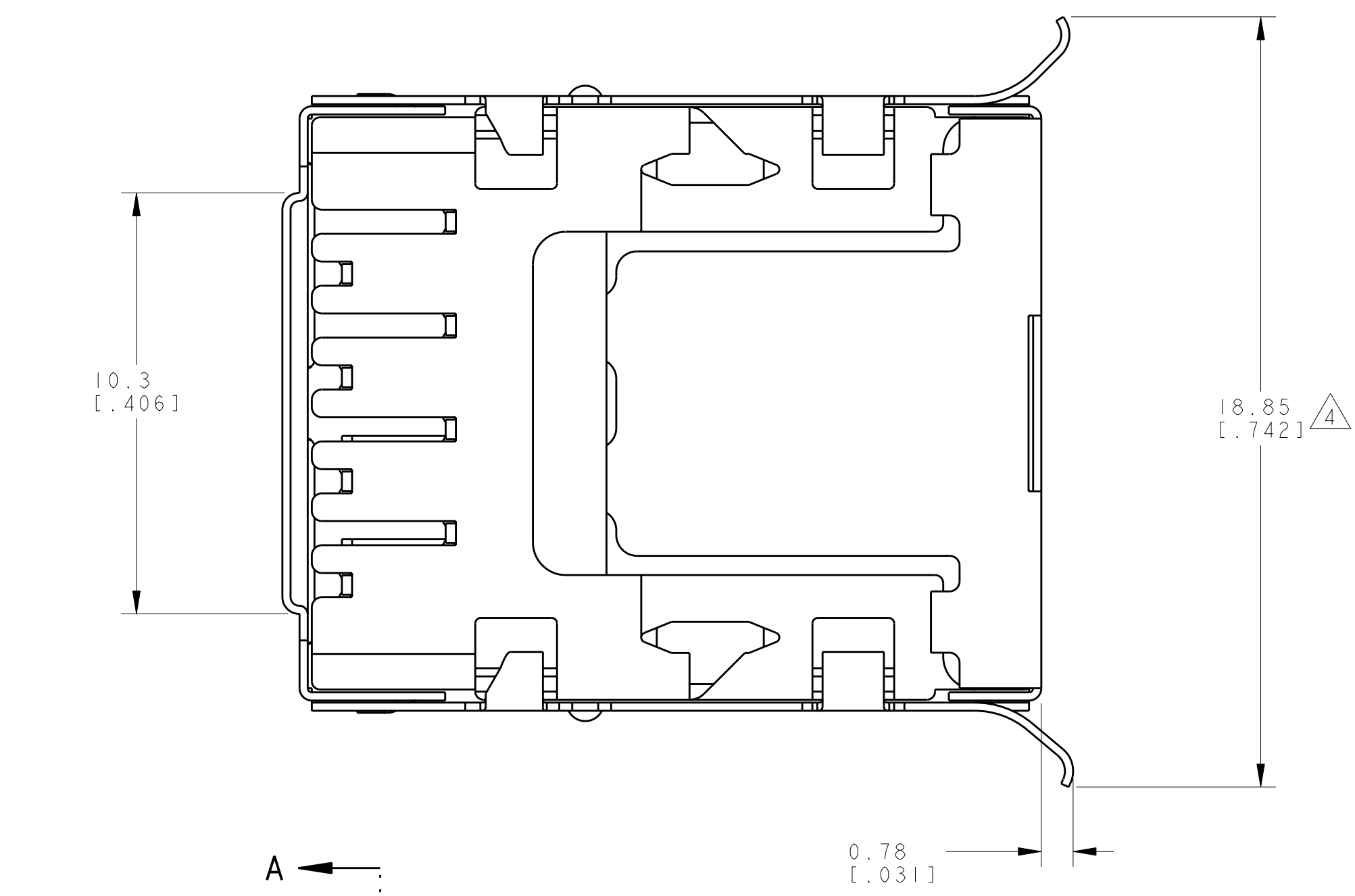


| LOC | DIST | REV | DESCRIPTION | DATE | BY | APPD |
|-----|------|-----|---------------------------|-----------|----|------|
| AA | 22 | M1 | REVISED PER ECO-11-005027 | 12MAY2011 | RK | HMR |
| | | N | ECO-11-021965 | 30JAN2012 | JJ | AC |
| | | P | ECR-11-023692 | 13FEB2012 | JJ | AC |



- 1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, IR REFLOW SOLDERING PROCESS COMPATIBLE. TERMINALS - 0.25 [0.010] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm [0.000150] MINIMUM THICK BRIGHT TIN-LEAD IN SOLDER AREA, 1.27µm [0.00050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [0.00050] MINIMUM THICK NICKEL. SHIELD - 0.1 [0.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0µm [0.00079-.00157] THICK TIN OVER 1.27µm [0.00050] MIN THICK NICKEL.
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3 THIS DIMENSION REPRESENTS THE TOTAL HEIGHT OF THE CONNECTOR FROM THE TOP OF THE PC BOARD.
- 4 THIS DIMENSION HAS A MAXIMUM VALUE OF 20.50 [0.807] WHEN JACK IS INSTALLED BEHIND PANEL.
- 5. PACKAGED 66 ASSEMBLIES PER PVC TRAY, 396 PER BOX.
- 6 MANUFACTURING DATE CODE: ORIENTED AND LOCATED APPROXIMATELY AS SHOWN, BLACK INK STAMP. TEXT HEIGHT APPROXIMATELY 2MM.
FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR
NEXT 2 DIGITS = MANUFACTURING WORK WEEK
LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1
- 7 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, IR REFLOW SOLDERING PROCESS COMPATIBLE. TERMINALS - 0.25 [0.010] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm [0.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm [0.00050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [0.00050] MINIMUM THICK NICKEL. SHIELD - 0.1 [0.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0µm [0.00079-.00157] THICK TIN OVER 1.27µm [0.00050] MIN THICK NICKEL.
- 8 PACKED WITH TAPE AND REEL PACKAGE.
- 9 MATERIAL: SHIELD - 0.1 [0.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 1.27µm [0.00050] MIN THICK NICKEL, PCB GROUND TABS DIPPED WITH 2.03µm [0.00080] MIN TIN. OTHER COMPONENT: AS SAME AS 7



| REV | DESCRIPTION | DATE | BY | APPD |
|-----|-------------|------|----|------|
| 9 | 1116062-4 | | | |
| 7 | 1116062-3 | | | |
| 1 | 1116062-2 | | | |
| 1 | 1116062-1 | | | |

THIS DRAWING IS A CONTROLLED DOCUMENT.

| | | | |
|-------------------------|--|-------------------|------------------|
| DIMENSIONS: | TOLERANCES UNLESS OTHERWISE SPECIFIED: | DWN: J. AHERON | 11NOV98 |
| mm [INCHES] | 9 PLC ± | CHK: D. KEMPKA | 11NOV98 |
| | 3 PLC ± | APVD: D. KEMPKA | 11NOV98 |
| | 5 PLC ± | NAME: | |
| | 4 PLC ± | PRODUCT SPEC: | 108-1163 |
| | ANGLES ± | APPLICATION SPEC: | 114-2048 |
| MATERIAL: SEE P/N TABLE | FINISH: SEE P/N TABLE | WEIGHT: | 3.49 grams |
| | | CUSTOMER DRAWING: | A100779C=1116062 |

STE TE Connectivity
MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, 10mm

SCALE: 8:1 SHEET 1 OF 1 REV P